

Data sheet Product ICK S R 32,5 x 10



Heatsinks and active heatsinks for processors>Pin heatsinks

Ø 32.5 x 10 mm, pin heatsinks round

Features

design:	round
way of fixation:	• therm. conductive foil • therm. cond. adhesive
socket:	universal
suitable for processor type:	universal
diameter:	32.5 mm
height:	10 mm
plate thickness:	3 mm
weight:	9.7 g
thermal resistance:	11.9 - 2 K/W
dissipation loss:	5.04 W
surface:	Al-natural

Technical Drawing

